

**Highlights of
the Import and Export (Strategic Commodities) Regulations
(Amendment of Schedules 1 and 2) Order 2001**

The major changes brought about by the Import and Export (Strategic Commodities) Regulations (Amendment of Schedules and 2) Order 2001 are highlighted as follows :

Classification Code Changes

Munitions List

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| ML3 | - Remove the control on cartridges specially designed for signalling, bird scaring or lighting of gas flares at oil wells. |
| ML4 | - Remove the control on hand-held devices for bomb detection equipment. |
| ML17 | - Add the control on test models specially designed for the "development" of items controlled by ML4, ML6, ML9 or ML10;
- Add control on bridges designed for military use. |
| ML19 | - Add the control on continuous wave or pulsed laser systems specially designed to cause permanent blindness to un-enhanced vision. |

Dual-use Goods List

Category 0 – Nuclear Materials, Facilities and Equipment

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| 0B/0C | - Add the control on UCl ₄ system;
- De-control nuclear grade graphite of less than 1kg. |
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Category 1 – Materials, Chemicals, Microorganisms, and Toxins

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| 1A002 | - De-control the organic matrix used for civil applications, such as for sporting goods. |
| 1C | - Tighten the control on the elastic limit of uranium titanium from 1,250 MPa to 880 MPa;
- Add the control on waste or scrap of hafnium metal;
- De-control botulinum toxins for medical application. |
| 1E | - Add new paragraph for the control on technology used for the production of base materials or non-composite ceramic materials. |

Classification Code **Changes**

Category 2 – Material Processing

- 2B
- Revise existing and add new references;
 - Add the control on heat exchangers or condensers of silicon carbide and titanium carbide;
 - Add the control on CVD furnace, process equipment for rocket nozzles;
 - Add the word “tangential” to the terminology for “cross (tangential) flow filtration equipment”;
 - Relax the control limits on special purpose machine tools limited to the manufacturing of any of the following parts: a) Crank shafts or cam shafts; b) Tools or cutters; c) Extruder worms; d) Engraved or faceted jewelry parts”;
 - Add the control on fly cutting machines.
- 2D001
- Amend the entry heading to read "software, other than that controlled by 2D002".
- 2E003
- Revise the Deposition Techniques Table by (1) adding new resultant coatings technologies for diamond, boron nitride, and beryllium, and (2) updating the sensor window materials note by including diamond, gallium phosphide, sapphire, zirconium fluoride and hafnium fluoride.

Category 3 – Electronics

- 3A001
- Relax the CTP control on microprocessors from 3,500 to 6,500 Mtops;
 - Increase the gate count control on digital integrated circuits from 300 to 3,000;
 - Unify the names for field programmable gate arrays and logic arrays as field programmable logic devices;
 - Relax the conversion time control on A/D converters from 10ns to 5ns;
 - Relax the control on custom integrated circuits from 208 to 1,000 terminals and the propagation delay time from 0.35ns to 0.1ns;
 - Relax the control on rated execution time of N-point FFT processors to less than $(N \log_2 N)/20,480$ ms;
 - Add new note for ITU allocated bands:
Relax control on the electromagnetic amplification for super-conductive materials parts.
- 3A002
- Liberalize control on digital video magnetic tape recorders from 180 to 360 Mbits/s;
 - De-control digital video magnetic tape recorders specially designed

Classification Code

Changes

- for civil television applications;
 - Relax the real time bandwidth control on dynamic signal analyzer from 25.6 kHz to 500 kHz;
 - De-control dynamic signal analyzers which employ only constant percentage bandwidth filters.
- 3B001
- Add control on molecular beam epitaxial growth equipment using solid sources;
 - Clarify types of lithography equipment;
 - Relax the control on lithography equipment with light source wavelength down to 350nm and a resolvable feature size down to 0.5 microns or less;
- 3B002
- Relax the control limit on test equipment for semiconductor devices. De-control semiconductor testing equipment for memories testing.
- 3C001
- Add control on silicon carbide as substrate.
- 3C002
- Relax the wavelength control on positive resists for semiconductor lithography from 370 nm to 350 nm.
- 3E001
- Clarify that 3E001 do not control integrated circuits using technology of 0.7 microns or more.
- 3E002
- Add control on substrates of silicon-on-insulator (SOI) for integrated circuits in which the insulator is silicon dioxide and substrates of silicon carbide for electronic components.

Category 4 – Computers

- 4A003
- Relax the CTP control on digital computers from 6,500 to 28,000 Mtops;
 - Relax the 3D vector rate control on graphic accelerators from 3 million to 200 million;
 - Relax the data rate control on external interconnection of computers from 80 Mbyte/s to 1.25 Gbyte/s.
- 4D003
- De-control expert system.

Category 5, Part 1 – Telecommunications

- 5B001/5D001
- De-control radio equipment above 31 GHz;
 - Liberalise the control on software, which provides the capability of recovering source code of telecommunication software controlled by 5D001.

<u>Classification Code</u>	<u>Changes</u>
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5E001	- Add new note for ITU allocated bands.
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Category 5, Part 2 – Information Security

5A002/5D002	- Liberalise the control on generally available encryption products.
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Category 6 – Sensors and Lasers

6A003	- Reduce control on acoustic projectors, hydrophones and towed acoustic hydrophone arrays; - Clarify under which conditions that 6A003(b)(4) do not control imaging cameras incorporating linear focal plane arrays; - Clarify the criterion to evaluate instrumentation cameras with modular structures.
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6A004	- Add control on certain aspheric optical elements.
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6A005	- Add a note for excimer lasers, specially designed for lithography equipment; - Add control on arrays of semiconductor lasers.
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6C002	- Relax control on cadmium zinc telluride.
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Category 7 – Navigation and Avionics

7A002	- Add new control on angular or rotational accelerometers.
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Category 8 – Marine

8A002	- Add note to clarify that self-contained rebreathing diving and underwater swimming apparatus are not controlled when accompanying its user and for personal use.
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Category 9 – Propulsion Systems, Space Vehicles and Related Equipment

9B001	- De-control ceramic core and ceramic shell wax pattern equipment for the manufacturing of gas turbine engine parts; - De-control equipment for measuring gas turbine products.
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9D	- Add new software control on ceramic core and ceramic shell wax pattern equipment for the manufacturing of gas turbine engine parts; Add control on software, which coordinates the function of more than - one subsystem in space launch vehicles or sounding rockets.
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<u>Classification Code</u>	<u>Changes</u>
9E002	- Add new note to clarify the technology control on gas turbine engine under repair, rebuild and overhaul.
9E003	- Add a new paragraph of technology control on composite materials used in gas turbine engine components or engines; - De-control the relevant technology on rotor blade tip clearance control system.

The above list is for reference only. For details of the amendments, please refer to the Import and Export (Strategic Commodities) Regulations (Amendment of Schedules 1 & 2) Order 2001. For details of the strategic commodities control list, in addition to the above-mentioned Amendment Order, please also refer to the Schedules to the Import and Export (Strategic Commodities) Regulations.